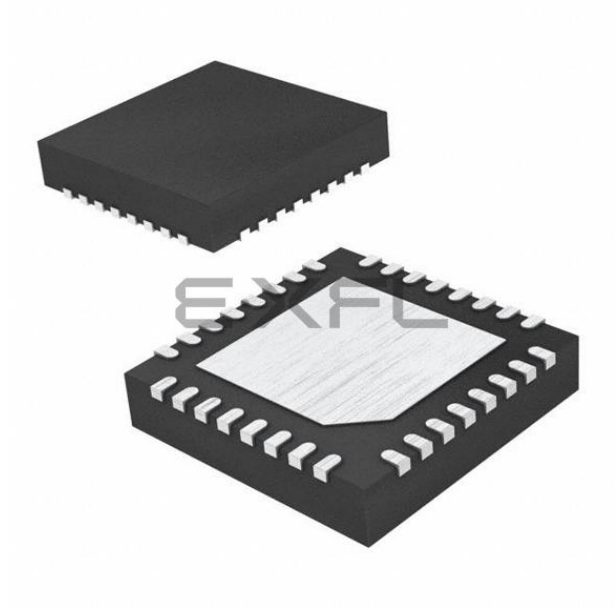
Microchip Technology - DSPIC33EP16GS502-I/MM Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 12x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep16gs502-i-mm

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

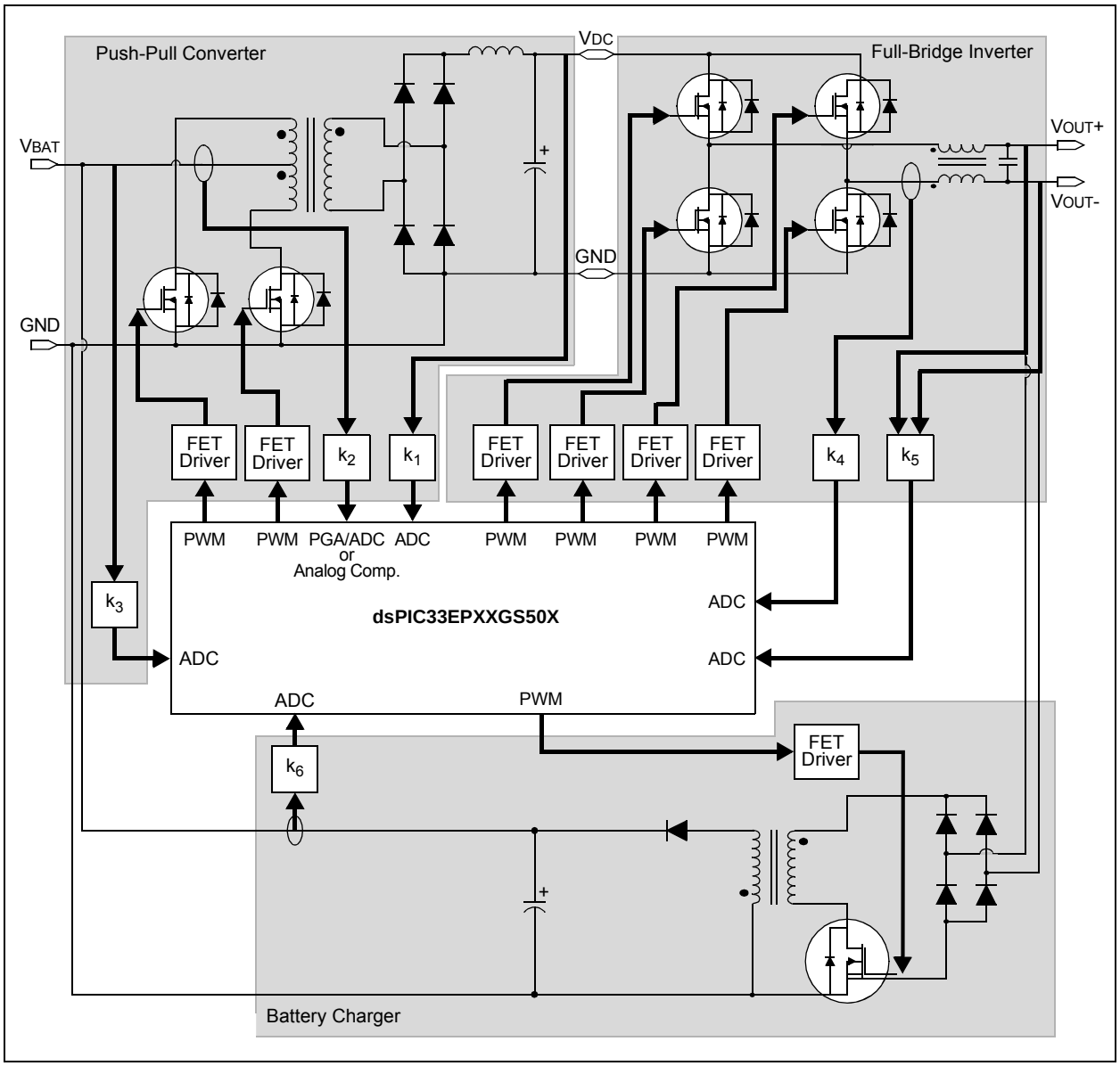
Pin Name(1)	Pin Type	Buffer Type	PPS	Description
$\overline{MCLR}$	I/P	ST	No	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	P	P	No	Positive supply for analog modules. This pin must be connected at all times.
AVSS	P	P	No	Ground reference for analog modules. This pin must be connected at all times.
VDD	P	—	No	Positive supply for peripheral logic and I/O pins.
VCAP	P	—	No	CPU logic filter capacitor connection.
VSS	P	—	No	Ground reference for logic and I/O pins.

Legend: CMOS = CMOS compatible input or output
Analog = Analog input
P = Power
ST = Schmitt Trigger input with CMOS levels
O = Output
I = Input
PPS = Peripheral Pin Select
TTL = TTL input buffer

1: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

2: These pins are dedicated on 64-pin devices.

FIGURE 2-6: OFF-LINE UPS



REGISTER 8-2: CLKDIV: CLOCK DIVISOR REGISTER (CONTINUED)

bit 4-0 **PLLPRE<4:0>:** PLL Phase Detector Input Divider Select bits (also denoted as 'N1', PLL prescaler)
11111 = Input divided by 33
•
•
•
00001 = Input divided by 3
00000 = Input divided by 2 (default)

Note 1: The DOZE<2:0> bits can only be written to when the DOZEN bit is clear. If DOZEN = 1, any writes to DOZE<2:0> are ignored.
2: This bit is cleared when the ROI bit is set and an interrupt occurs.
3: The DOZEN bit cannot be set if DOZE<2:0> = 000. If DOZE<2:0> = 000, any attempt by user software to set the DOZEN bit is ignored.

REGISTER 8-3: PLLFBD: PLL FEEDBACK DIVISOR REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	PLLDIV8
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
PLLDIV<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as '0'

bit 8-0 **PLLDIV<8:0>:** PLL Feedback Divisor bits (also denoted as 'M', PLL multiplier)
111111111 = 513
•
•
•
000110000 = 50 (default)
•
•
•
000000010 = 4
000000001 = 3
000000000 = 2

9.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Watchdog Timer and Power-Saving Modes"** (DS70615) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXGS50X family devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of peripherals being clocked constitutes lower consumed power.

dsPIC33EPXXGS50X family devices can manage power consumption in four ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

9.1 Clock Frequency and Clock Switching

The dsPIC33EPXXGS50X family devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 8.0 "Oscillator Configuration"**.

9.2 Instruction-Based Power-Saving Modes

The dsPIC33EPXXGS50X family devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the PWRSAV instruction is shown in Example 9-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

EXAMPLE 9-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into Sleep mode
PWRSAV  #IDLE_MODE     ; Put the device into Idle mode
```

REGISTER 10-38: RPOR18: PERIPHERAL PIN SELECT OUTPUT REGISTER 18

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP181R5	RP181R4	RP181R3	RP181R2	RP181R1	RP181R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP180R5	RP180R4	RP180R3	RP180R2	RP180R1	RP180R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP181R<5:0>:** Peripheral Output Function is Assigned to RP181 Output Pin bits (see Table 10-2 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP180R<5:0>:** Peripheral Output Function is Assigned to RP180 Output Pin bits (see Table 10-2 for peripheral function numbers)

REGISTER 19-11: ADCOREXL: DEDICATED ADC CORE x CONTROL REGISTER LOW (x = 0 to 3)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	SAMC<9:8>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SAMC<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 **Unimplemented:** Read as '0'

bit 9-0 **SAMC<9:0>:** Dedicated ADC Core x Conversion Delay Selection bits

These bits determine the time between the trigger event and the start of conversion in the number of the Core Clock Periods (TADCORE). During this time, the ADC Core x still continues sampling. This feature is enabled by the SAMCxEN bits in the ADCON4L register.

1111111111 = 1025 TADCORE

•

•

•

0000000001 = 3 TADCORE

0000000000 = 2 TADCORE

REGISTER 19-27: ADTRIGxH: ADC CHANNEL TRIGGER x SELECTION REGISTER HIGH (x = 0 to 5) (CONTINUED)

bit 4-0 **TRGSRC(4x+2)<4:0>:** Trigger Source Selection for Corresponding Analog Inputs bits

11111 = ADTRG31
11110 = Reserved
11101 = Reserved
11100 = PWM Generator 5 current-limit trigger
11011 = PWM Generator 4 current-limit trigger
11010 = PWM Generator 3 current-limit trigger
11001 = PWM Generator 2 current-limit trigger
11000 = PWM Generator 1 current-limit trigger
10111 = Output Compare 2 trigger
10110 = Output Compare 1 trigger
10101 = Reserved
10100 = Reserved
10011 = PWM Generator 5 secondary trigger
10010 = PWM Generator 4 secondary trigger
10001 = PWM Generator 3 secondary trigger
10000 = PWM Generator 2 secondary trigger
01111 = PWM Generator 1 secondary trigger
01110 = PWM secondary Special Event Trigger
01101 = Timer2 period match
01100 = Timer1 period match
01011 = Reserved
01010 = Reserved
01001 = PWM Generator 5 primary trigger
01000 = PWM Generator 4 primary trigger
00111 = PWM Generator 3 primary trigger
00110 = PWM Generator 2 primary trigger
00101 = PWM Generator 1 primary trigger
00100 = PWM Special Event Trigger
00011 = Reserved
00010 = Level software trigger
00001 = Common software trigger
00000 = No trigger is enabled

20.3 Module Applications

This module provides a means for the SMPS dsPIC® DSC devices to monitor voltage and currents in a power conversion application. The ability to detect transient conditions and stimulate the dsPIC DSC processor and/or peripherals, without requiring the processor and ADC to constantly monitor voltages or currents, frees the dsPIC DSC to perform other tasks.

The comparator module has a high-speed comparator and an associated 12-bit DAC that provides a programmable reference voltage to the inverting input of the comparator. The polarity of the comparator output is user-programmable. The output of the module can be used in the following modes:

- Generate an Interrupt
- Trigger an ADC Sample and Convert Process
- Truncate the PWMx Signal (current limit)
- Truncate the PWMx Period (current minimum)
- Disable the PWMx Outputs (Fault latch)

The output of the comparator module may be used in multiple modes at the same time, such as: 1) generate an interrupt, 2) have the ADC take a sample and convert it, and 3) truncate the PWMx output in response to a voltage being detected beyond its expected value.

The comparator module can also be used to wake-up the system from Sleep or Idle mode when the analog input voltage exceeds the programmed threshold voltage.

20.4 Digital-to-Analog Comparator (DAC)

Each analog comparator has a dedicated 12-bit DAC that is used to program the comparator threshold voltage via the CMPxDAC register. The DAC voltage reference source is selected using the EXTREF and RANGE bits in the CMPxCON register.

The EXTREF bit selects either the external voltage reference, EXTREFx, or an internal source as the voltage reference source. The EXTREFx input enables users to connect to a voltage reference that better suits their application. The RANGE bit enables AV_{DD} as the voltage reference source for the DAC when an internal voltage reference is selected.

Note: EXTREF2 is not available on all devices.

Each DACx has an output enable bit, DACOE, in the CMPxCON register that enables the DACx reference voltage to be routed to an external output pin (DACOUTx). Refer to Figure 20-1 for connecting the DACx output voltage to the DACOUTx pins.

Note 1: Ensure that multiple DACOE bits are not set in software. The output on the DACOUTx pin will be indeterminate if multiple comparators enable the DACx output.

2: DACOUT2 is not available on all devices.

20.5 Pulse Stretcher and Digital Logic

The analog comparator can respond to very fast transient signals. After the comparator output is given the desired polarity, the signal is passed to a pulse stretching circuit. The pulse stretching circuit has an asynchronous set function and a delay circuit that ensures the minimum pulse width is three system clock cycles wide to allow the attached circuitry to properly respond to a narrow pulse event.

The pulse stretcher circuit is followed by a digital filter. The digital filter is enabled via the FLTREN bit in the CMPxCON register. The digital filter operates with the clock specified via the FCLKSEL bit in the CMPxCON register. The comparator signal must be stable in a high or low state, for at least three of the selected clock cycles, for it to pass through the digital filter.

REGISTER 20-1: CMPxCON: COMPARATOR x CONTROL REGISTER (CONTINUED)

bit 5 **EXTREF:** Enable External Reference bit
1 = External source provides reference to DACx (maximum DAC voltage is determined by the external voltage source)
0 = AVDD provides reference to DACx (maximum DAC voltage is AVDD)

bit 4 **HYSPOL:** Comparator Hysteresis Polarity Select bit
1 = Hysteresis is applied to the falling edge of the comparator output
0 = Hysteresis is applied to the rising edge of the comparator output

bit 3 **CMPSTAT:** Comparator Current State bit
Reflects the current output state of Comparator x, including the setting of the CMPPOL bit.

bit 2 **ALTINP:** Alternate Input Select bit
1 = INSEL<1:0> bits select alternate inputs
0 = INSEL<1:0> bits select comparator inputs

bit 1 **CMPPOL:** Comparator Output Polarity Control bit
1 = Output is inverted
0 = Output is non-inverted

bit 0 **RANGE:** DACx Output Voltage Range Select bit
1 = AVDD is the maximum DACx output voltage
0 = Unimplemented, do not use

Note 1: DACOUTx can be associated only with a single comparator at any given time. The software must ensure that multiple comparators do not enable the DACx output by setting their respective DACOE bit.

REGISTER 21-1: PGAxCON: PGAx CONTROL REGISTER (CONTINUED)

bit 2-0 **GAIN<2:0>:** PGAx Gain Selection bits
111 = Reserved
110 = Gain of 64x
101 = Gain of 32x
100 = Gain of 16x
011 = Gain of 8x
010 = Gain of 4x
001 = Reserved
000 = Reserved

REGISTER 21-2: PGAxCAL: PGAx CALIBRATION REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	PGACAL<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as ‘0’

bit 5-0 **PGACAL<5:0>:** PGAx Offset Calibration bits
The calibration values for PGA1 and PGA2 must be copied from Flash addresses, 0x800E48 and 0x800E4C, respectively, into these bits before the module is enabled. Refer to the calibration data address table (Table 23-3) in **Section 23.0 “Special Features”** for more information.

TABLE 23-2: CONFIGURATION BITS DESCRIPTION

Bit Field	Description
BSS<1:0>	Boot Segment Code-Protect Level bits 11 = Boot Segment is not code-protected other than BWRP 10 = Standard security 0x = High security
BSEN	Boot Segment Control bit 1 = No Boot Segment is enabled 0 = Boot Segment size is determined by the BSLIM<12:0> bits
BWRP	Boot Segment Write-Protect bit 1 = Boot Segment can be written 0 = Boot Segment is write-protected
BSLIM<12:0>	Boot Segment Flash Page Address Limit bits Contains the last active Boot Segment page. The value to be programmed is the inverted page address, such that programming additional '0's can only increase the Boot Segment size (i.e., 0x1FFD = 2 Pages or 1024 IW).
GSS<1:0>	General Segment Code-Protect Level bits 11 = User program memory is not code-protected 10 = Standard security 0x = High security
GWRP	General Segment Write-Protect bit 1 = User program memory is not write-protected 0 = User program memory is write-protected
CWRP	Configuration Segment Write-Protect bit 1 = Configuration data is not write-protected 0 = Configuration data is write-protected
CSS<2:0>	Configuration Segment Code-Protect Level bits 111 = Configuration data is not code-protected 110 = Standard security 10x = Enhanced security 0xx = High security
BTSWP	BOOTSWP Instruction Enable/Disable bit 1 = BOOTSWP instruction is disabled 0 = BOOTSWP instruction is enabled
BSEQ<11:0>	Boot Sequence Number bits (Dual Partition modes only) Relative value defining which partition will be active after device Reset; the partition containing a lower boot number will be active.
IBSEQ<11:0>	Inverse Boot Sequence Number bits (Dual Partition modes only) The one's complement of BSEQ<11:0>; must be calculated by the user and written for device programming. If BSEQx and IBSEQx are not complements of each other, the Boot Sequence Number is considered to be invalid.
AIVTDIS(1)	Alternate Interrupt Vector Table bit 1 = Alternate Interrupt Vector Table is disabled 0 = Alternate Interrupt Vector Table is enabled if INTCON2<8> = 1
IESO	Two-Speed Oscillator Start-up Enable bit 1 = Starts up device with FRC, then automatically switches to the user-selected oscillator source when ready 0 = Starts up device with the user-selected oscillator source
PWMLOCK	PWMx Lock Enable bit 1 = Certain PWMx registers may only be written after a key sequence 0 = PWMx registers may be written without a key sequence

Note 1: The Boot Segment must be present to use the Alternate Interrupt Vector Table.

TABLE 26-23: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SY00	TPU	Power-up Period	—	400	600	μs	
SY10	TOST	Oscillator Start-up Time	—	1024 TOSC	—	—	TOSC = OSC1 period
SY12	TWDT	Watchdog Timer Time-out Period	0.81	—	1.22	ms	WDTPRE = 0, WDTPOST<3:0> = 0000, using LPRC tolerances indicated in F21 (see Table 26-21) at +85°C
			3.25	—	4.88	ms	WDTPRE = 1, WDTPOST<3:0> = 0000, using LPRC tolerances indicated in F21 (see Table 26-21) at +85°C
SY13	TIOZ	I/O High-Impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	0.68	0.72	1.2	μs	
SY20	TMCLR	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	
SY30	TBOR	BOR Pulse Width (low)	1	—	—	μs	
SY35	TFSCM	Fail-Safe Clock Monitor Delay	—	500	900	μs	-40°C to +85°C
SY36	TVREG	Voltage Regulator Standby-to-Active mode Transition Time	—	—	30	μs	
SY37	TOSCDFRC	FRC Oscillator Start-up Delay	—	48	—	μs	
SY38	TOSCDLPRC	LPRC Oscillator Start-up Delay	—	—	70	μs	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 3.3V, +25°C unless otherwise stated.

FIGURE 26-16: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

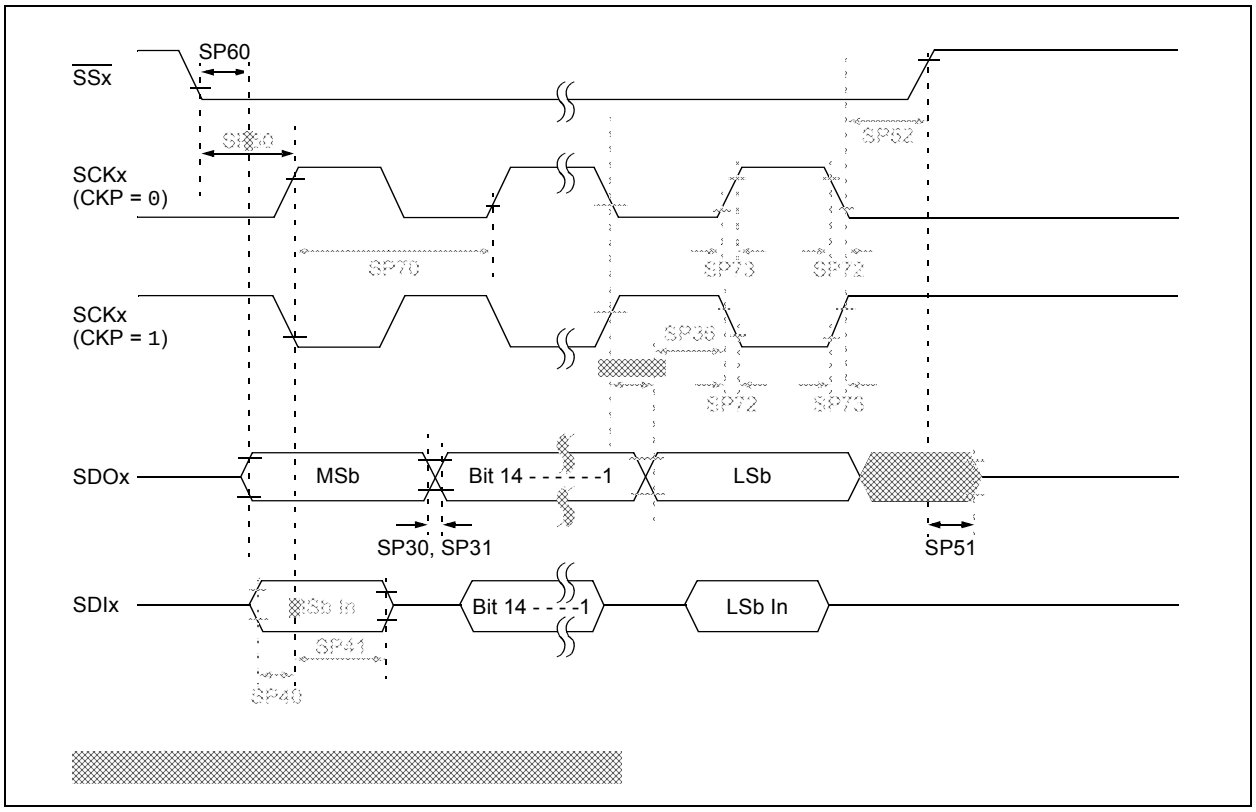


TABLE 26-48: PGAx MODULE SPECIFICATIONS

AC/DC CHARACTERISTICS(1)				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**		**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
PA01	VIN	Input Voltage Range		AVSS – 0.3	—	AVDD + 0.3	V	
PA02	VCM	Common-Mode Input Voltage Range		AVSS	—	AVDD – 1.6	V	
PA03	VOS	Input Offset Voltage		-10	—	10	mV	
PA04	VOS	Input Offset Voltage Drift with Temperature		—	±15	—	µV/°C	
PA05	RIN+	Input Impedance of Positive Input		—	>1M || 7 pF	—	Ω|| pF	
PA06	RIN-	Input Impedance of Negative Input		—	10K || 7 pF	—	Ω|| pF	
PA07	GERR	Gain Error		-2	—	2	%	Gain = 4x, 8x
				-3	—	3	%	Gain = 16x
				-4	—	4	%	Gain = 32x, 64x
PA08	LERR	Gain Nonlinearity Error		—	—	0.5	%	% of full scale, Gain = 16x
PA09	IDD	Current Consumption		—	2.0	—	mA	Module is enabled with a 2-volt P-P output voltage swing
PA10a	BW	Small Signal Bandwidth (-3 dB)	G = 4x	—	10	—	MHz	
PA10b			G = 8x	—	5	—	MHz	
PA10c			G = 16x	—	2.5	—	MHz	
PA10d			G = 32x	—	1.25	—	MHz	
PA10e			G = 64x	—	0.625	—	MHz	
PA11	OST	Output Settling Time to 1% of Final Value		—	0.4	—	µs	Gain = 16x, 100 mV input step change
PA12	SR	Output Slew Rate		—	40	—	V/µs	Gain = 16x
PA13	TGSEL	Gain Selection Time		—	1	—	µs	
PA14	TON	Module Turn On/Setting Time		—	—	10	µs	

Note 1: The PGAx module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

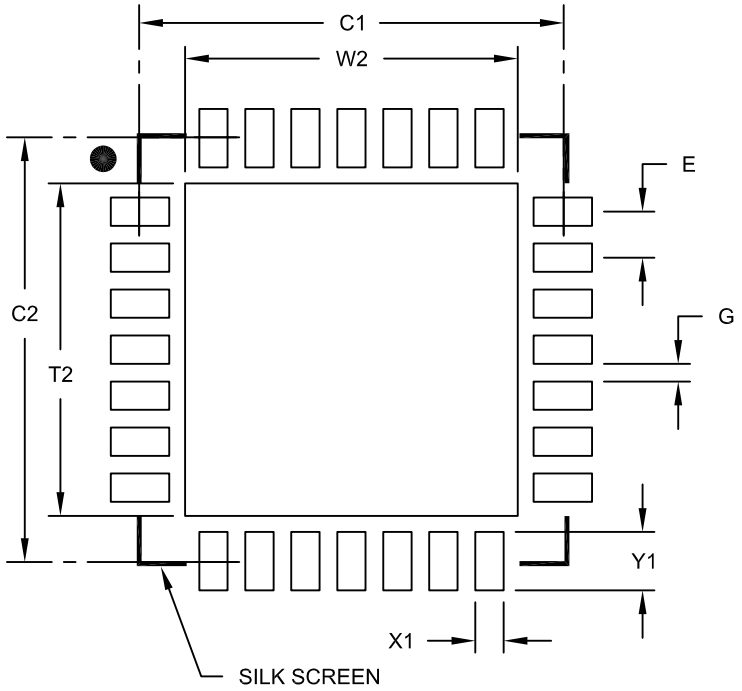
TABLE 26-49: CONSTANT-CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS(1)				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
CC01	IDD	Current Consumption	—	30	—	µA	
CC02	IREG	Regulation of Current with Voltage On	—	±3	—	%	
CC03	IOUT	Current Output at Terminal	—	10	—	µA	

Note 1: The constant-current source module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			4.70
Optional Center Pad Length	T2			4.70
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.40
Contact Pad Length (X28)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

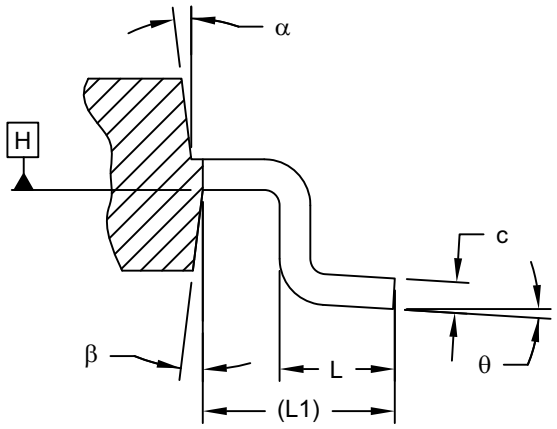
1. Dimensioning and tolerancing per ASME Y14.5M

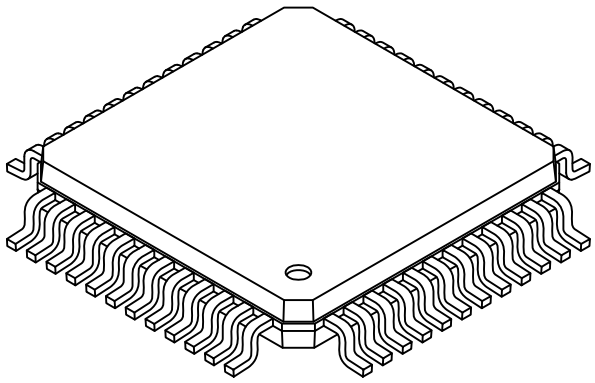
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A

48-Lead Thin Quad Flatpack (Y8) - 7x7x1.0 mm Body [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





SECTION A-A

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		48	
Lead Pitch	e		0.50 BSC	
Overall Height	A	-	-	1.20
Standoff	A1	0.05	-	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		9.00 BSC	
Overall Length	D		9.00 BSC	
Molded Package Width	E1		7.00 BSC	
Molded Package Length	D1		7.00 BSC	
Lead Thickness	c	0.09	-	0.16
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A-B and D to be determined at center line between leads where leads exit plastic body at datum plane H

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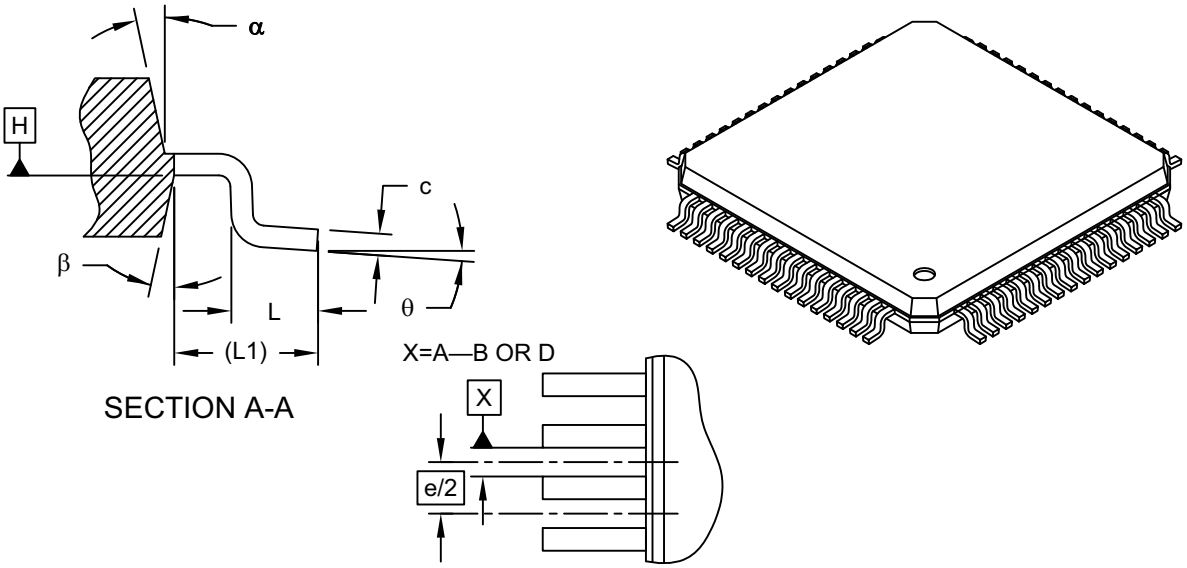
64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	-	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

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APPENDIX A: REVISION HISTORY

Revision A (June 2013)

This is the initial released version of the document.

Revision B (May 2015)

Adds dsPIC33EPXXGS505 (48-pin) devices to the document:

- Amends the table on page 2 to add the three new devices of this group
- Adds the 48-pin TQFP pin diagram on page 7
- Amends Table 26-3 to include thermal packaging characteristics for 48-pin packages
- Updates **Section 28.1 "Package Marking Information"** to include package marking details for 48-pin TQFP devices
- Updates **Section 28.2 "Package Details"** to include Microchip Drawings C04-183A and C04-2183A (7x7x1.0 mm 48-lead TQFP)

Changes all references to Dual Boot Flash Program Memory throughout the text to "Dual Partition Flash Program Memory". In addition, all accompanying references to "panels" and "Boot modes" are changed to "partitions" and "Partition modes". This includes, but is not limited, to:

- **Section 4.1 "Program Address Space"**
- **Section 5.4 "Dual Partition Flash Configuration"**, and Register 5-1
- **Section 23.10 "Code Protection and CodeGuard™ Security"**, and Table 23-2

Replaces the high-speed pipeline A/D Converter present in pre-production samples with a high-speed, multiple SAR A/D Converter in production devices:

- Replaces **Section 19.0 "High-Speed, 12-Bit Analog-to-Digital Converter (ADC)"** with an entirely new section of the same title, replacing all previous figures and registers
- Updates the summary bullet points under "High-Speed ADC Module" on Page 1 to reflect the feature set of the new module
- Updates Table 4-3 and Table 7-1 to reflect the new module's interrupt structure
- Replaces Table 4-16 with a new register map
- Removes Table 4-16 ("ADC Calibration Register Map"); subsequent tables are renumbered accordingly
- Updates **Section 23.2 "Device Calibration and Identification"** and Table 23-3 to remove the ADCAL registers from the Calibration register table
- Removes all references to the internal temperature sensor, including Table 26-44 (Temperature Sensor Specifications) and Figure 27-11 (Typical Temperature Sensor Voltage vs. Current)

Changes the ESR specification of the V_{CAP} filter capacitor from < 4Ω to < 0.5Ω.

Removes the internal voltage reference in all occurrences. For analog modules, the internal band gap reference is substituted as a replacement source.

Changes the following register names in all occurrences throughout the text:

- "CMPCONx" to "CMPxCON"
- "CMPDACx" to "CMPxDAC"
- "I2CxCON1" to "I2CxCONL"
- "I2CxCON2" to "I2CxCONH"

Updates the text of **Section 5.4.2 "Dual Partition Modes"** to change "Untrusted Dual Panel mode" to "Privileged Dual Partition mode" and clarifies the mode's code security features.

Changes the BSS2 Configuration bit to "BSEN" throughout the text.

Replaces **Section 23.3 "User OTP Memory"** with new text to describe the 64-word User OTP Memory space; also removes Table 23-4.

Amends Table 24-2 with a footnote indicating an increase of instruction execution cycles for most instructions under certain conditions.

Updates the following tables in **Section 26.0 "Electrical Characteristics"** (in addition to changes previously noted):

- Table 26-4, with new specification DC12 (and accompanying footnote)
- Table 26-6, with updated Typical and new Maximum data throughout, and the addition of Parameter DC27 (with accompanying footnote)
- Table 26-7, Table 26-8 and Table 26-10 with updated Typical and Maximum data throughout
- Table 26-9 with updated Typical and Maximum data for Parameters DC61a and DC61b
- Footnotes 6 and 7 of Table 26-11 to clarify the behavior of 5V tolerant pins
- The "ADC Accuracy" specifications of Table 26-43
- Table 26-45 (Table 26-45 in Revision A) with updated specifications for Parameter CM15
- Table 26-46 (Table 26-46 in Revision A) with updated specifications for Parameters DA03 through DA06

Clarifies the text of Footnotes 6 and 7 in Table 26-11 (I/O Pin Input Specifications).

Removes the "Reference Inputs" specifications from Table 26-43 in their entirety.

Replaces Figure 27-5 through Figure 27-10 with new characterization graphs to reflect the most current data and removes "TBD" watermarks.

Updates **Section 28.1 "Package Marking Information"** to reflect the removal of redundant temperature and package code information from all package markings; this is in addition to the new 48-pin package markings previously described.

Other minor typographic corrections throughout the document.

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